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156

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10027919	12/20/2001	205	291	1741	Wong

**APPLICANTS: Seita Masaru; Tsuchida Hideki; Hayashi Shinjiro;

1453

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

JAPAN 2000-387865 12/20/2000

PG-PUB DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☐ yes ☐ no

35 USC 119 conditions met ☐ yes ☐ no

Verified and Acknowledged Examiners's initials

ATTORNEY DOCKET NO

51343

TITLE : Electrolytic copper plating solution and method for controlling the same

U.S. DEPT. OF COMM /PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED		
		Total Claims		Print Claim for O.G
Assistant Examiner				
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.	Print Fig.
		Primary Examiner		
		Application Examiner		
<input checked="" type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE		
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